MA2ZD14

Silicon epitaxial planar type

For high speed switching

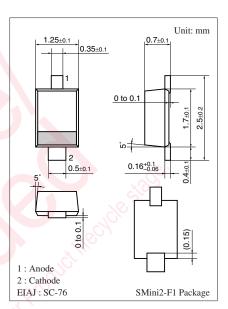
■ Features

• Low forward voltage: V_F < 0.40 V

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol Rating		Unit	
Reverse voltage	V_R	20	V	
Repetitive peak reverse voltage	V _{RRM}	20	V	
Forward current (Average)	I _{F(AV)}	100	mA	
Peak forward current	I_{FM}	300	mA	
Non-repetitive peak forward surge current *	I _{FSM}	1	A	
Junction temperature	Tj	125	°C	
Storage temperature	T_{stg}	-55 to +125	°C	

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

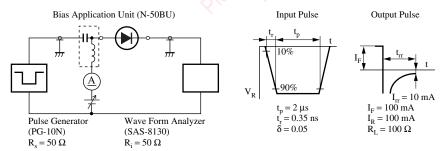


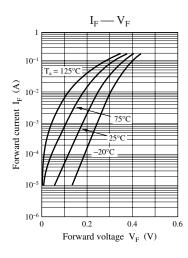
Marking Symbol: 2N

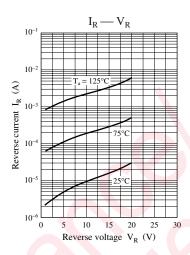
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage		V_{F1}	$I_F = 5 \text{ mA}$, /C	0.27	V
		V _{F2}	$I_F = 100 \text{ mA}$	100	0,	0.40	
Reverse current		I_R	$V_R = 10 \text{ V}$).	20	μΑ
Terminal capacitance		C_t	$V_R = 0 V, f = 1 MHz$	160	25		pF
Reverse recovery time *		t _{rr}	$I_F = I_R = 100 \text{ mA}$		3		ns
	7C, C, C		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 250 MHz.
 - 4. *: t_{rr} measurement circuit







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